

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t1181acn#pbf

(Engineering Calculation)

PDIP

(printed on: 2020-07-11 20:04:55)

**TOTAL MASS (g) : 1.02197**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.004091	1000000	4003.05297852		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.313072	975000	306341.65625		
		Iron (Fe)	7439-89-6	0.007706	24000	7540.33886719		
		Phosphorus (P)	7723-14-0	0.000096	300	93.9362182617		
		Zinc (Zn)	7440-66-6	0.000225	700	220.163009644		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.321099</b>	<b>1000000</b>	<b>314196.125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.024547	1000000	24019.28125		
		<b>External Plating Total:</b>				<b>0.024547</b>	<b>1000000</b>	<b>24019.28125</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.002569	1000000	2513.77246094		
<b>Internal Plating Total:</b>				<b>0.002569</b>	<b>1000000</b>	<b>2513.77246094</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001120	750000	1095.92260742		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000373	250000	364.981323242		
<b>Die Attach Total:</b>				<b>0.001493</b>	<b>1000000</b>	<b>1460.90393066</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.090126	135000	88188.5		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.574136	860000	561793.375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.003338	5000	3266.24072266		
		<b>Encapsulation Total:</b>				<b>0.667600</b>	<b>1000000</b>	<b>653248.0625</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000571	1000000	558.72479248		
					<b>TOTAL MASS (g) :</b>	<b>1.02197</b>		